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(71) Applicant *(for all designated States except US)*: **INNOPAD, INC.** [US/US]; 6 Centennial Drive, Peabody, MA 01960 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **HSU, Oscar, K.** [US/US]; 255 North Road, Chelmsford, MA 01824 (US). **LEFEVRE, Paul** [FR/US]; 8 High Ridge Road, Topsfield, MA 01983 (US). **WELLS, David Adam** [US/US]; 4 Melba Drive, Hudson, NH 03051 (US). **JIN, Marc** [US/US]; 1 Glouseter Street, Apt. 5, Boston, MA 02115 (US). **ALDEBORGH, John, Erik** [US/US]; 56 Boren Lane, Boxford, MA 01921 (US).

(74) Agents: **GROSSMAN, Steven, J.** et al.; Grossman, Tucker, Perreault & Pfleger, PLLC, 55 South Commercial Street, Manchester, NH 03101 (US).

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(54) Title: THREE-DIMENSIONAL NETWORK IN CMP PAD

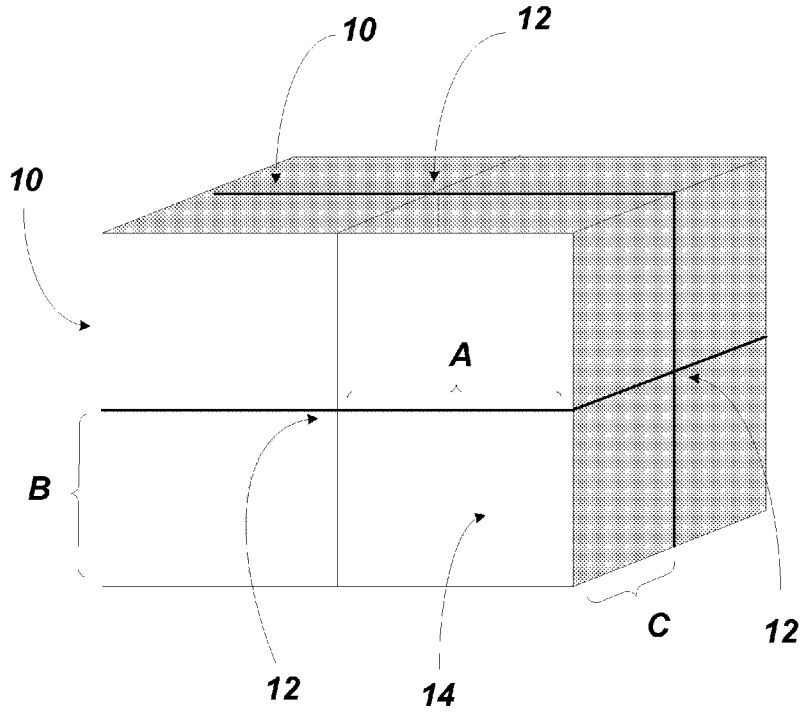

FIG. 1

(57) Abstract: The present disclosure is directed at a chemical-mechanical planarization polishing pad comprising interconnecting elements and a polymer filler material, wherein the interconnecting elements include interconnecting junction points that are present at a density of 1 interconnecting junction point/cm^3 to 1000 interconnecting junction points/cm^3, and wherein the interconnecting elements have a length between interconnection junction points of 0.1 microns to 20 cm.

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